

DDR4 ULTRA LOW PROFILE MEMORY MODULE SOCKETS



SPECIALLY DESIGNED SOCKETS FOR LOW PROFILE SYSTEM

DDR4 Ultra Low Profile (ULP) vertical DIMM sockets provide 288 contacts on 0.85mm pitch and facilitate convenient memory expansion in servers, workstations, desktop PCs, and embedded applications in communications and industrial equipment.

- Ultra low module seating height of 1.1mm
- Lowest connector height of 13.1mm
- Reduced overall profile of the connector
- Compatible with standard DIMM module to help optimize airflow
- Low resistance contacts (registered DIMM) reduces power consumption in hardware

FEATURES

- Ultra low module seating height of 1.1mm
- Low connector height of 13.1mm and 19.3mm
- Profiled contact design
- Multi-tail length
- Compact connector footprint of 6.5mm (W) by 152mm (L)
- RoHS compliant, low halogen and Lead-Free



BENEFITS

- Allows low profile server design
- Supports standard DIMM module to optimize airflow
- Reduces terminal and housing stress during module insertion
- Supports 1.6mm or 2.4mm thick motherboards
- Reduces valuable board space and cost
- Meets environmental requirements

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TECHNICAL INFORMATION

MATERIAL

- Contact : Copper Alloy
- Contact Finish:
 - Contact Area: 15µin. , 20µin. or 30µin. Gold, 30µin. GXT™ or Gold Flash over Nickel
 - Termination Area: Tin over Nickel
- Forklock: Copper Alloy
- Housing & Ejector: High Temperature Thermoplastic, UL94V-0

MECHANICAL PERFORMANCE

- Durability: 25 mating cycles

APPROVALS AND CERTIFICATIONS

- UL E66906

PACKAGING

- Tray

ELECTRICAL PERFORMANCE

- Contact Resistance: $\leq 10\text{m}\Omega$ initial, $\leq 10\text{m}\Omega$ increase after environmental test
- Current Rating: 0.75A/contact (De-rated) with $\leq 30^\circ\text{C}$ temperature rise above ambient

SPECIFICATIONS

- Product Specification: GS-12-1092
- Packaging Specification: GS-14-2267
- Application Specification: GS-20-0353
- JEDEC
 - Module Outline: MO-309
 - Socket Outline: SO-016 (PTH Solder)

TARGET MARKETS/APPLICATIONS



Switches
Router
Wireless Infrastructure



Server
Storage System
Supercomputer
Workstation
Desktop PC



Embedded System

PART NUMBERS

Description	Termination Option	Color	Part Number
DDR4 Ultra Low Profile Plated Through Hole (ULP PTH)	Solder- termination with forklocks	Housing: Black, Natural, Blue Ejectors: Black, Natural, Blue	10129206

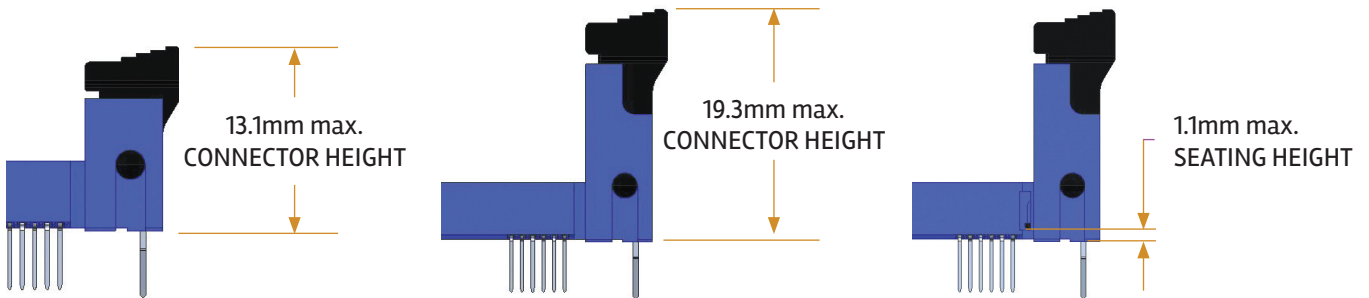
Disclaimer

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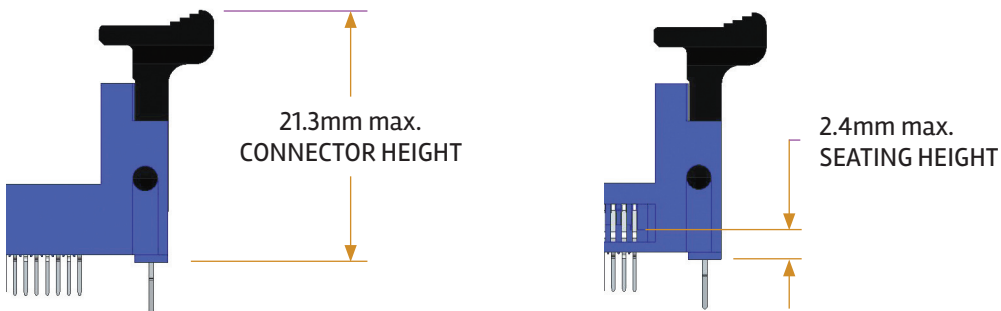
CONNECTOR DIMENSIONS

DDR4 ULP offers lower seating and connector height. Compatible with standard DIMM module, the overall height can be reduced significantly from 21.3mm to 13.1mm. DDR4 ULP allows customer to improve on the airflow and addresses the need for low profile server design, in applications such as 1U server, micro server, industrial/communication applications.

DDR4 ULTRA LOW PROFILE



DDR4 STANDARD



Disclaimer

Please note that the above information is subject to change without notice.